

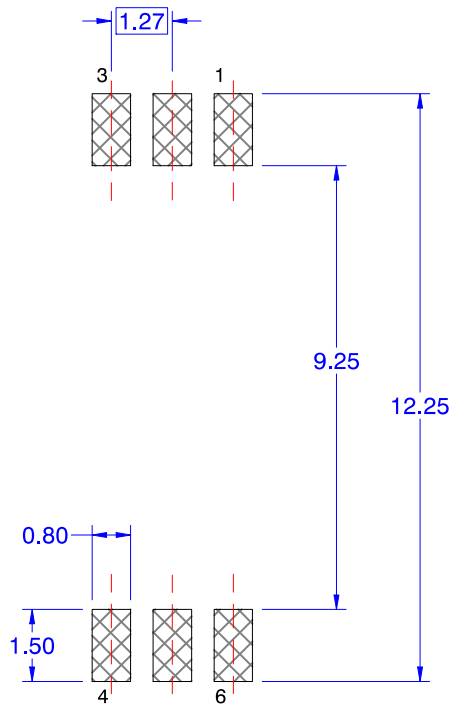
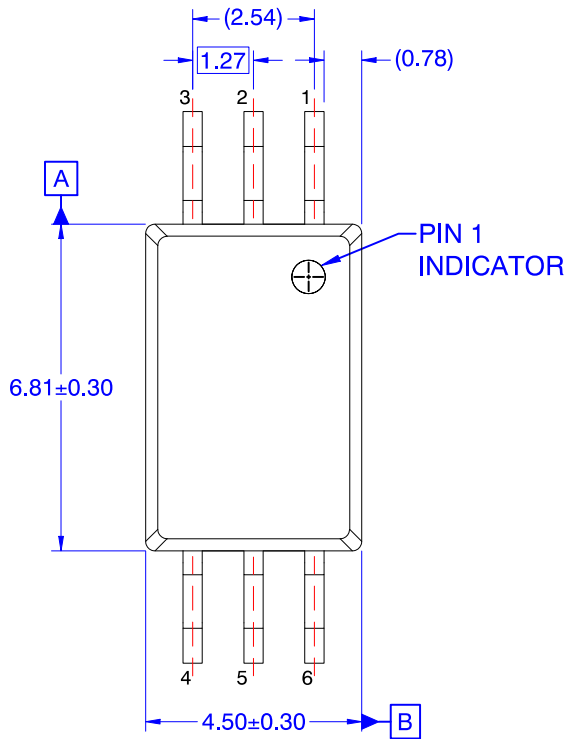
**MECHANICAL CASE OUTLINE**  
**PACKAGE DIMENSIONS**

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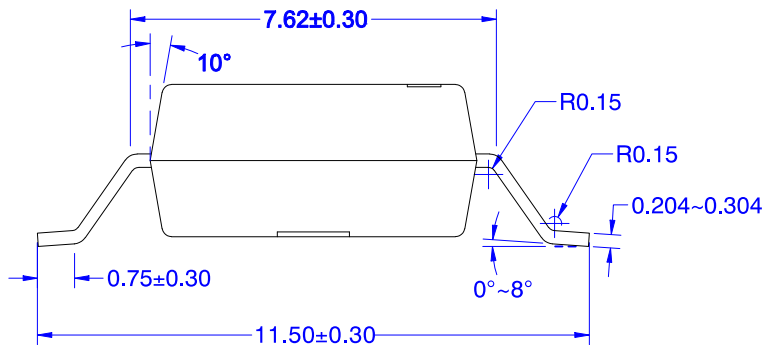
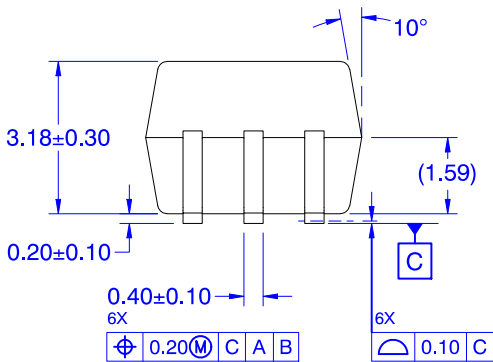


**SOIC6 W**  
**CASE 751EM**  
**ISSUE O**

DATE 30 SEP 2016



**RECOMMENDED LAND PATTERN**



- NOTES: UNLESS OTHERWISE SPECIFIED**
- A) NO STANDARD APPLIES TO THIS PACKAGE
  - B) ALL DIMENSIONS ARE IN MILLIMETERS.
  - C) DIMENSIONS DO NOT INCLUDE BURRS OR MOLD FLASH, AND TIE BAR EXTRUSION.
  - D) DIMENSIONING AND TOLERANCING PER ASME Y14.5M-2009.

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